DESCRIPTION

~~PROTECTIVE FILM FOR SEMICONDUCTOR WAFER, AND METHOD FOR MANUFACTURING SEMICONDUCTOR CHIP~~

TECHNICAL FIELD

[0001]

The present invention relates to a protective film for a semiconductor wafer and a method for manufacturing a semiconductor chip.

BACKGROUND ART

[0002]

A flip chip interconnection method has been used for making a mounting area of a semiconductor chip small or reducing a height. In the connecting method, a wafer which has a circuit and a connecting bump on its surface is subjected to dicing to obtain a semiconductor chip, the surface of the chip is faced to the substrate and connected, and then, resin sealing, etc., are carried out to protect the semiconductor chip.

[0003]

In the above-mentioned dicing process, it has been known a sheet for forming a protect film for a chip which is to prevent the chip from damaging by vibration, etc., of the rotary blade (hereinafter referred to as "chipping"), and also acts as a sealing film in place of resin sealing (PATENT LITERATURE 1, PATENT LITERATURE 2).

[0004]

Also, for the purpose of preventing twisting of an IC card, it has been known a card using a reinforcing material having a low linear expansion coefficient (PATENT LITERATURE 3), and a card using a reinforcing material for

DESCRIPTION

PROTECTIVE FILM FOR SEMICONDUCTOR WAFER AND METHOD FOR MANUFACTURING SEMICONDUCTOR CHIP

TECHNICAL FIELD

[0001]

The present invention relates to a protective film for a semiconductor wafer and a method for manufacturing a semiconductor chip.

BACKGROUND ART

[0002]

A flip chip interconnection method has been used for making a mounting area of a semiconductor chip small or reducing a height. In the connecting method, a wafer which has a circuit and a connecting bump on its surface is subjected to dicing to obtain a semiconductor chip, the surface of the chip is faced to the substrate and connected, and then, resin sealing, etc., are carried out to protect the semiconductor chip.

[0003]

In the above-mentioned dicing process, it has been known a sheet for forming a protect film for a chip which is to prevent the chip from damaging by vibration, etc., of the rotary blade (hereinafter referred to as "chipping"), and also acts as a sealing film in place of resin sealing (PATENT LITERATURE 1, PATENT LITERATURE 2).

[0004]

Also, for the purpose of preventing twisting of an IC card, it has been known a card using a reinforcing material having a low linear expansion coefficient (PATENT LITERATURE 3), and a card using a reinforcing material for